

1. FOR GENERAL SERIES SPECIFICATIONS, SEE SDXX-0000.

BODY: BRASS, NICKEL PLATE
HOUSING: BRASS, GOLD PLATE
CONTACT: BERYLLIUM COPPER, GOLD PLATE
INSULATOR: PTFE, NATURAL

IMPEDANCE: 75 OHMS
FREQUENCY RANGE: DC-12 GHz
RETURN LOSS: <-15 dB UP TO 6.0 GHz
DIELECTRIC WITHSTANDING VOLTAGE: 1000VRMS MIN.
INSULATION RESISTANCE:10,000 MEGOHMS MIN.

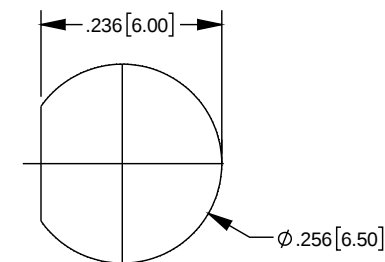
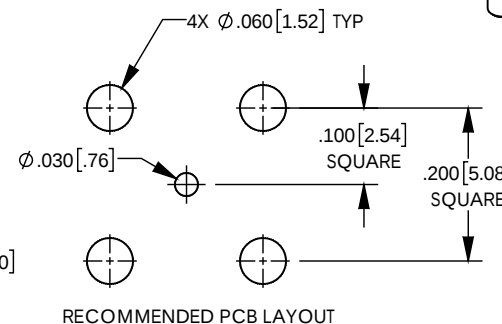
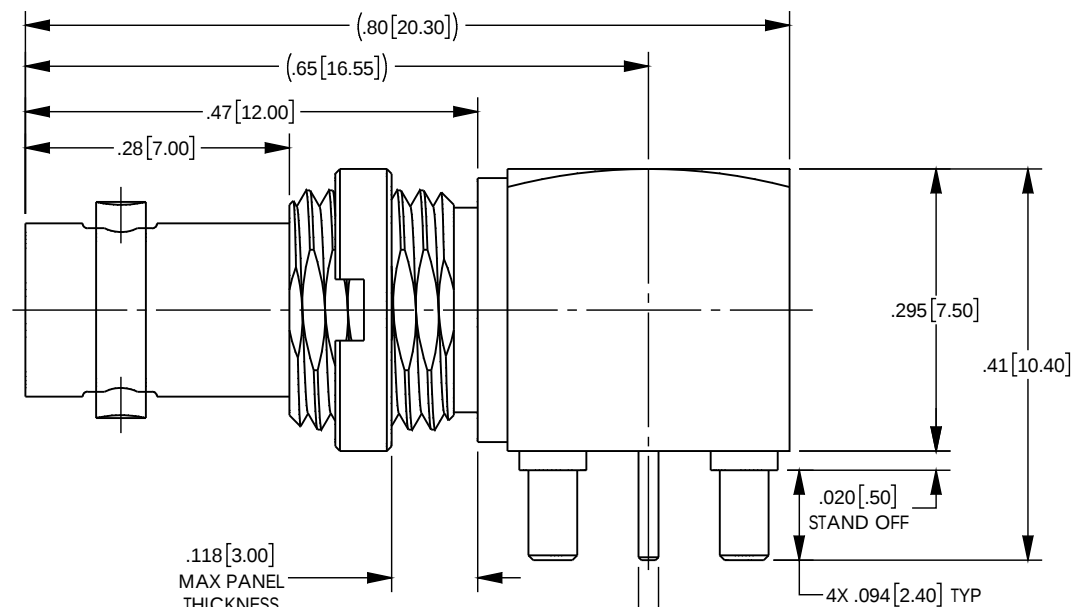
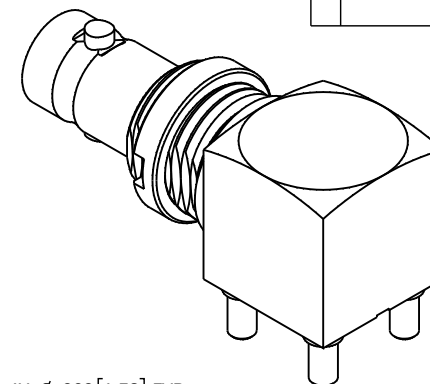
DURABILITY: 500 CYCLES MIN

THERMAL SHOCK PER MIL-STD-202 METHOD 107
 TEST CONDITIONS B (EXCEPT HIGH TEMP @200° C)
 VIBRATION: MIL-STD-202 METHOD 204 TEST CONDITION B
 SHOCK: MIL-STD-202 METHOD 213 TEST CONDITION B
 CORROSION: MIL-STD-202 METHOD 101
 TEST CONDITIONSB 5% SALT SOLUTION

INDIVIDUALLY BAGGED

7. COMPLIANT TO 3G/6G/12G-SDI SMPTE REQUIREMENTS.

REV	DESCRIPTION	BY DATE	APP
B	ER063190	06/06/16	YA



RECOMMENDED MOUNTING HOLE

CATALOG P/N: HHD364HDE704

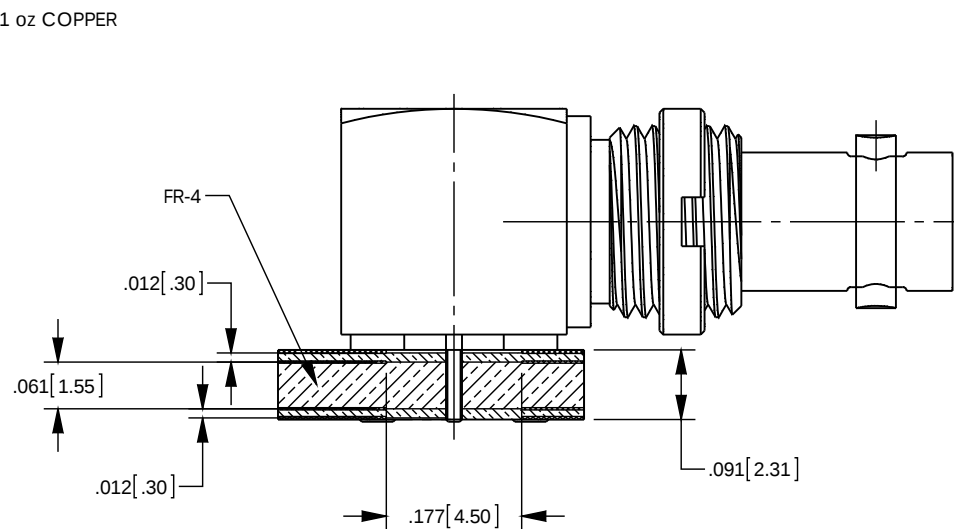
PER ASME Y14.5M-1994 UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN INCHES [MM] TOLERANCES: DECIMAL: .XX [X.X] ± .01 [0.3] .xxx [X.XX] ± .005 [0.13] .xxxx [X.XXXX] ± .xxxx				 KINGS[®] by WINCHESTER ELECTRONICS				Winchester Electronics Corporation 199 Park Road Ext Suite 104 Middlebury, Connecticut 06762						
ANGLES: ± 2° SCALE: 5:1				THIRD ANGLE 		HD-BNC RA BHD JACK PCB MOUNT								
CUSTOMER SALES DRAWING														
DRAWN KPL		DATE 11/22/13		APPROVED MS		DATE 11/22/13								
APPROVED XXX		DATE XX/XX/XX		APPROVED XXX		DATE XX/XX/XX		A		SDHHD364HDE704		SHT 1	OF 2	REV B

VARIATIONS IN BOARD DIELECTRIC MATERIAL AND TRACE ROUTING MAY REQUIRE DIFFERENT GEOMETRY
(STANDARD FR-4 EPOXY IS ASSUMED HERE, $\epsilon_r=4.40$)

Technical drawing of a microstrip antenna patch on a substrate. The drawing shows a central circular patch with four smaller circular pads at the corners. Dimensions are given in inches and millimeters. Key features include a plated thru hole, a 75 OHM trace, and various pad sizes.

Dimensions and Labels:

- $\phi .030 [.76]$ PLATED THRU HOLE
- $.009 [.23]$ (75 OHM TRACE)
- $.040 [1.02]$
- $.200 [5.08]$
- $.100 [2.54]$
- $\phi .072 [1.83]$ PAD SIZE
- $\phi .177 [4.50]$
- $\phi .045 [1.14]$ PAD SIZE



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01	PRELIMINARY DRAWING ER050504	11/22/2013	MS
02	UPDATED PCB LAYOUT FOR TOP OF HP3064DE/04 PER ER051495	01/22/14	YA

PER ASME Y14.5M-1994
UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN INCHES
TOLERANCES:
DECIMAL: .XX ± .XX
 .XXX ± .XXX
 .XXXX ± .XXXX

ANGLES: :
MATERIAL

FINISH			

DRAWN	DATE	APPROVED	DATE
KPL	11/22/2013	MS	06/17/2016
APPROVED	DATE	APPROVED	DATE
XXX	XX/XX/XX	XXX	XX/XX/XX

THIRD
ANGLE



WINCHESTER
ELECTRONICS

Winchester Electronics Corporation
199 Park Road Ext Suite 104
Middlebury, Connecticut 06762

HD BNC RA BHD JACK PCB MOUNT

A	SDHHD364HDE704	SHT 2	OF 2	REV 02
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